PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Toshiyuki HIGASHINO	07/28/2008

RECEIVING PARTY DATA

Name:	Elpida Memory, Inc.	
Street Address:	2-1, Yaesu 2-chome, Chuo-ku	
City:	Tokyo	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12183471

CORRESPONDENCE DATA

Fax Number: (516)742-4366

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

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Correspondent Name: SCULLY SCOTT MURPHY & PRESSER, PC

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ATTORNEY DOCKET NUMBER: 23122

NAME OF SUBMITTER: Paul J. Esatto, Jr.

Total Attachments: 2

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ASSIGNMENT

In consideration of One Dollar (\$1.00), and other good and valuable considerations, the receipt of which is hereby acknowledged, we, the undersigned,

Hereby sell, assign and transfer to Elpida Memory, Inc. a corporation of Japan having a place

f business at 2-1, Yaesu 2-chome, Chuo-ku, Tokyo, Japan its successors, assigns and legal representatives
he entire right, title and interest for all countries, in and to any and all improvements which are disclosed
nd claimed, and as possessed by the undersigned, any and all improvements which are disclosed but not
laimed, in the application for United States Patent, which has been executed by the undersigned
n July 28, 2008 and is entitled SEMICONDUCTOR
DEVICE AND METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE a
d in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other
pplications for Letters Patent which have been or shall be filed on any of said improvements disclosed in
aid application; and in and to all original and reissued patents which have been or shall be issued on said
mnrovements:

Authorize and request the Commissioner of Patents to issue to said Assignee, the corporation above named, its successors, assigns and legal representatives, in accordance with this assignment, any and all United States Letters Patent on said improvements, or any of them, disclosed in said application;

Agree that said Assignee may apply for and receive foreign Letters Patent for said improvements, or any of them; and may claim, in applications for said foreign Letters Patent, the priority of the aforesaid United States application under the provisions of the International Convention; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will, for the United States and all foreign countries, execute all divisional, continuing, substitute, renewal, reissue and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee its successors, assigns and representatives, all facts known to the undersigned relating to said improvements and the history thereof; testify in all legal proceedings; and generally do everything possible which said Assignee, its successors, assigns or representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said improvements and for vesting title to said improvements and all applications for

PATENT REEL: 021323 FRAME: 0954 patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Toshiyoki Higashino Toshiyuki HIGASHINO

Date:

July 28, 2008

RECORDED: 07/31/2008

Witness:

PATENT REEL: 021323 FRAME: 0955